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<table>
<thead>
<tr>
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<tbody>
<tr>
<td>1. A. Name of conveying party: Hisaki KURASHINA</td>
<td>2. A. Name and address of receiving party: SEIKO EPSON CORPORATION 4-1, NISHI-SHINJUKU 2-CHOME, SHINJUKU-KU, TOKYO, JAPAN</td>
</tr>
<tr>
<td>B. Additional name(s) of conveying party(ies) attached? ☒ Yes ☐ No</td>
<td>B. Additional name(s) &amp; address(es) attached? ☐ Yes ☒ No</td>
</tr>
<tr>
<td>3. A. Nature of conveyance: ☒ Assignment ☐ Merger ☐ Security Agreement ☐ Change of Name ☐ Other</td>
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<tr>
<td>B. Execution Date: February 2, 2004</td>
<td></td>
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<tr>
<td>4. A. If this document is being filed together with a new application, the execution date of the application is:</td>
<td></td>
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<tr>
<td>B. Patent Application No.(s) 10/751,971</td>
<td>C. Patent No.(s)</td>
</tr>
<tr>
<td>Additional numbers attached? ☐ Yes ☒ No</td>
<td></td>
</tr>
<tr>
<td>5. Name and address of party to whom correspondence concerning document should be mailed: Name: James A. Oliff</td>
<td>6. Total number of applications and patents involved: 1</td>
</tr>
<tr>
<td>Address: OLIFF &amp; BERRIDGE, PLC P.O. Box 19978 Alexandria, VA 22320 Phone Number: 703-836-6400 Fax Number: 703-836-2787</td>
<td></td>
</tr>
<tr>
<td>7. Please charge Deposit Account No. 15-0461 the total fee (37 CFR 3.41) in the amount of $40.00.</td>
<td></td>
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<tr>
<td>8. Credit any overpayment or charge any underpayment to deposit account number 15-0461.</td>
<td></td>
</tr>
<tr>
<td>9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</td>
<td>Date: April 16, 2004</td>
</tr>
</tbody>
</table>

James A. Oliff Registration No. 27,072
Thomas J. Pardini Registration No. 30,411
Assignment

For good and valuable consideration, the receipt of which is hereby acknowledged, I/WE, the undersigned,

Hisaki KURASHINA,

who have created a certain invention for which an application for United States Letters Patent

executed by ME/US on even date herewith,
executed by ME/US on __________ (respectively).
filed on January 7, 2004 and assigned Serial No. 10/751,871.
filed as International Application No. _______ filed on ________ and entitled:

TEST-ELEMENT-PROVIDED SUBSTRATE METHOD OF MANUFACTURING THE SAME SUBSTRATE FOR ELECTRO-OPTICAL DEVICE, ELECTRO-OPTICAL DEVICE, AND ELECTRONIC APPARATUS

Do hereby sell, assign and transfer to Seiko Epson Corporation, a corporation of Japan, having a place of business at 4-1, Nishi-shinjuku 2-chome, Shinjuku-ku, Tokyo, Japan, its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted thereafter in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Agree that Seiko Epson Corporation, hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and
セイコーエプソン株式会社の証明書

Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

IN TESTIMONY WHEREOF I/WE, the undersigned do further agree that this Assignment is to be construed solely according to the terms of the English language portions thereof.

IN TESTIMONY WHEREOF I/WE, the undersigned do further agree that this Assignment is to be construed solely according to the terms of the English language portions thereof.

上記を証明するため、私/私達は下記日付で署名する。

Full name of sole or first inventor
Hisaki KURASHINA

Inventor's signature
Date

2004年2月2日
Hisaki Kurashina
Feb. 2, 2004

Full name of second joint inventor, if any

Second Inventor's signature
Date

Full name of third joint inventor, if any

Third Inventor's signature
Date

Full name of fourth joint inventor, if any

Fourth Inventor's signature
Date

Full name of fifth joint inventor, if any

Fifth Inventor's signature
Date

Full name of sixth joint inventor, if any

Sixth Inventor's signature
Date

Full name of seventh joint inventor, if any

Seventh Inventor's signature
Date

Full name of eighth joint inventor, if any

Eighth Inventor's signature
Date